

MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

ON Semiconductor®

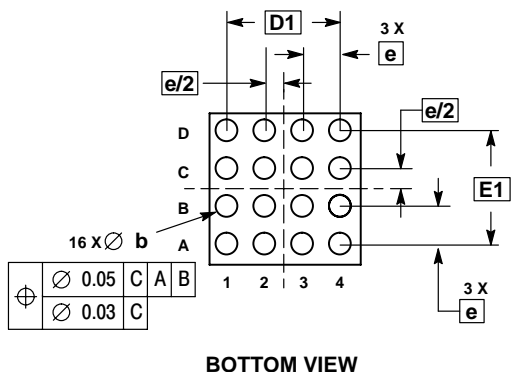
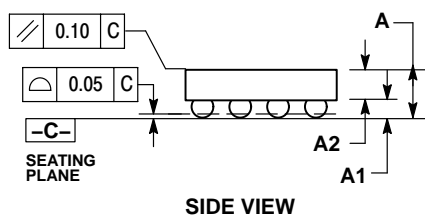
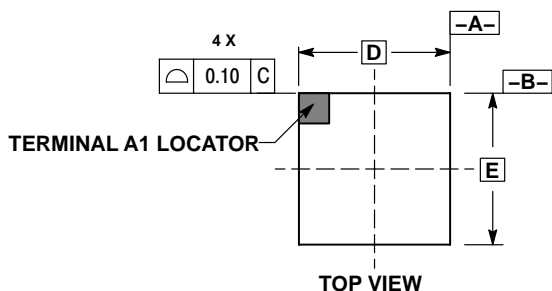


1

SCALE 4:1

16 PIN FLIP-CHIP
CASE 499AR-01
ISSUE A

DATE 23 FEB 2006



NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

MILLIMETERS		
DIM	MIN	MAX
A	---	0.650
A1	0.210	0.270
A2	0.280	0.380
D	2.050 BSC	
E	2.050 BSC	
b	0.290	0.340
e	0.500 BSC	
D1	1.500 BSC	
E1	1.500 BSC	

DOCUMENT NUMBER:	98AON21277D	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
STATUS:	ON SEMICONDUCTOR STANDARD	
NEW STANDARD:		
DESCRIPTION:	16 PIN FLIP-CHIP, 2.05 X 2.05 MM	PAGE 1 OF 2

